THER PUTTY 3SH-8-17000



Thermal Conductive Putty

THER PUTTY 3SH is a one-part dispensable material with thermal conductivity 8.0 W/m*K. High defor-mation can fill small air gaps perfectly to remove tolerance. It also can overcome overflow and drying problems to increase the thermal conductivity. THER PUTTY 3SH is a great alternative to thermal grease and ideally suited for dispensing using the dispensing robot.



FEATURES

/ Thermal conductivity:8.0 W/m*K

/ Bond line thickness:100-3000µm

/ Designed to remove manufacturing

tolerances

/ Does not produce stress on delicate components

/ No vertical flow

/ Dispensable for serial manufacture

/ For any high compression and low sress application

TYPICAL APPLICATION

/ Between CPU and heat sink

/ Between a component and heat sink

/ High speed mass storage drives

/ Telecommunication hardware

/ Flat-panel displays

/ Set-top box

/ IP CAM

/5G base station & infrastructure

/ EV electric vehicle

CONFIGURATIONS

/ Cartridges: 30ml, 55ml, 330ml

/ Bucket: 1kg, 25kg

PRESERVATION

HOW TO ORDER

Patron THER PUTTY 3SH-8-17000 XXX XXX = packaging

https://www.patron-components.com/

TYPICAL PROPERTIES

PROPERTY	PUTTY 3SH	TEST METHOD	UNIT
Color	Gray	Visual	-
Resin base	Silicone	-	-
Viscosity	17000	DIN 53018	Pa.s
Density	3.4	ASTM D792	g/cm³
Application temperature	-60~180	-	°C
Bond line thickness	100~3000	-	μm
Shelf life	60 months	-	-
ROHS & REACH	Compliant	-	-
ELECTRICAL			
Dielectric breakdown	12	ASTM D149	KV/mm
Volume resistivity	>1013	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	8.0	ASTM D5470	W/m*K
Thermal impedance@10psi	0.039	ASTM D5470	°C-in²/ W
Thermal impedance@30psi	0.035	ASTM D5470	°C-in²/ W
Thermal impedance@50psi	0.031	ASTM D5470	°C-in²/ W

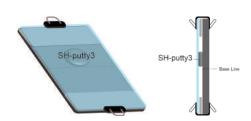
PLEASE NOTE

/ Using Automatic Homogenizer can improve the sedimentation phenomenon rapidly to achieve a homogeneous effect. We strongly recommend put cartridge in homogenizer for 3~5 minutes before dispensing the material.

Notice: if material homogenized more than 24 hours, it must be homogenized again while use it.

VERTICAL RELIABILITY

Using 3.0mm pad as a gap control, put the putty between the aluminum and the glass panel mark the initial position. Then, place it in the oven with 125°C for 1,000 hours and observe its displacement after reliability test



Material no dropped or changed afterhigh temperature aging testing